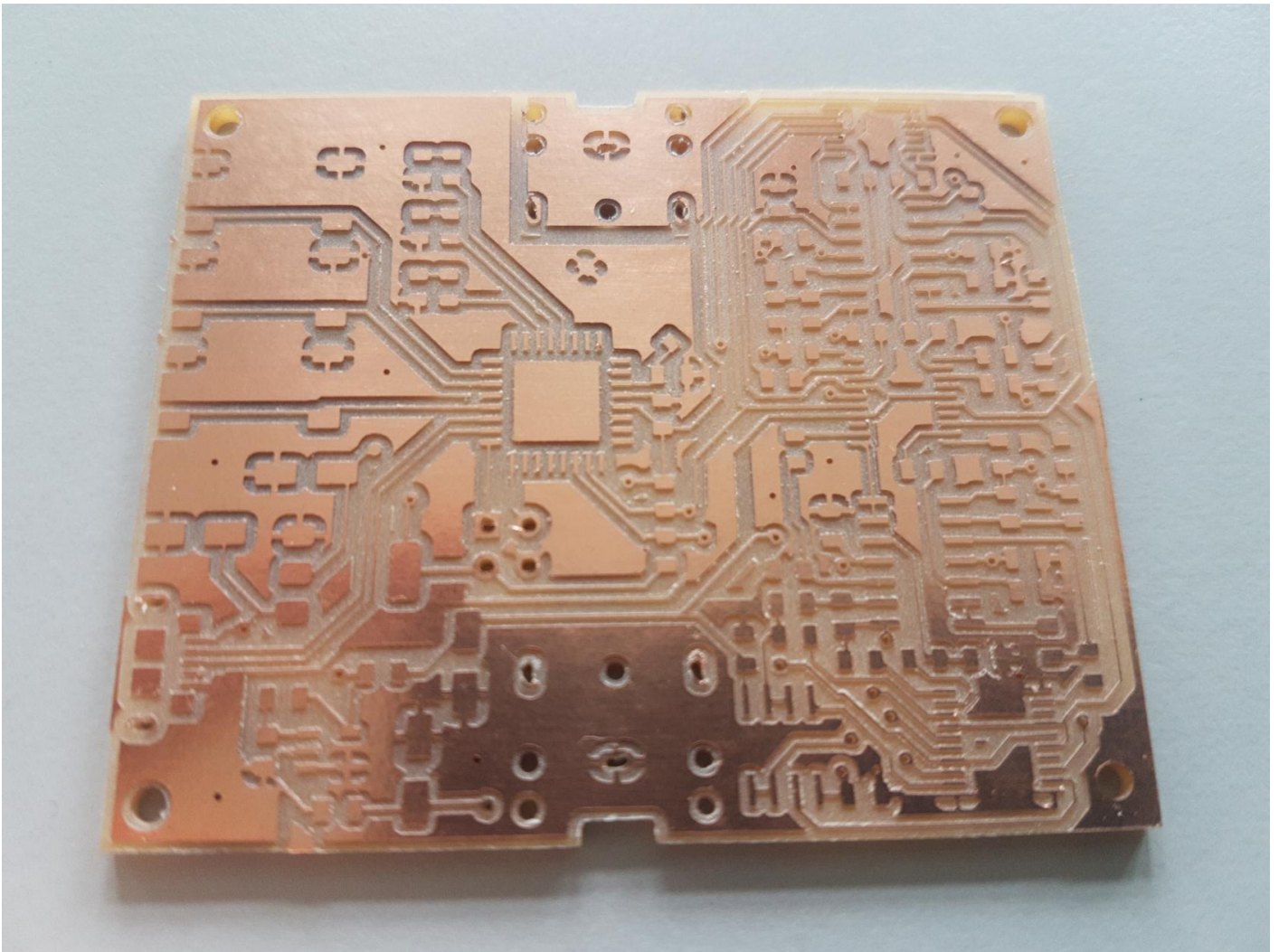


# Audio Tone Control

Thore Lencer, Prof. Dr.-Ing. Ralf Sommer

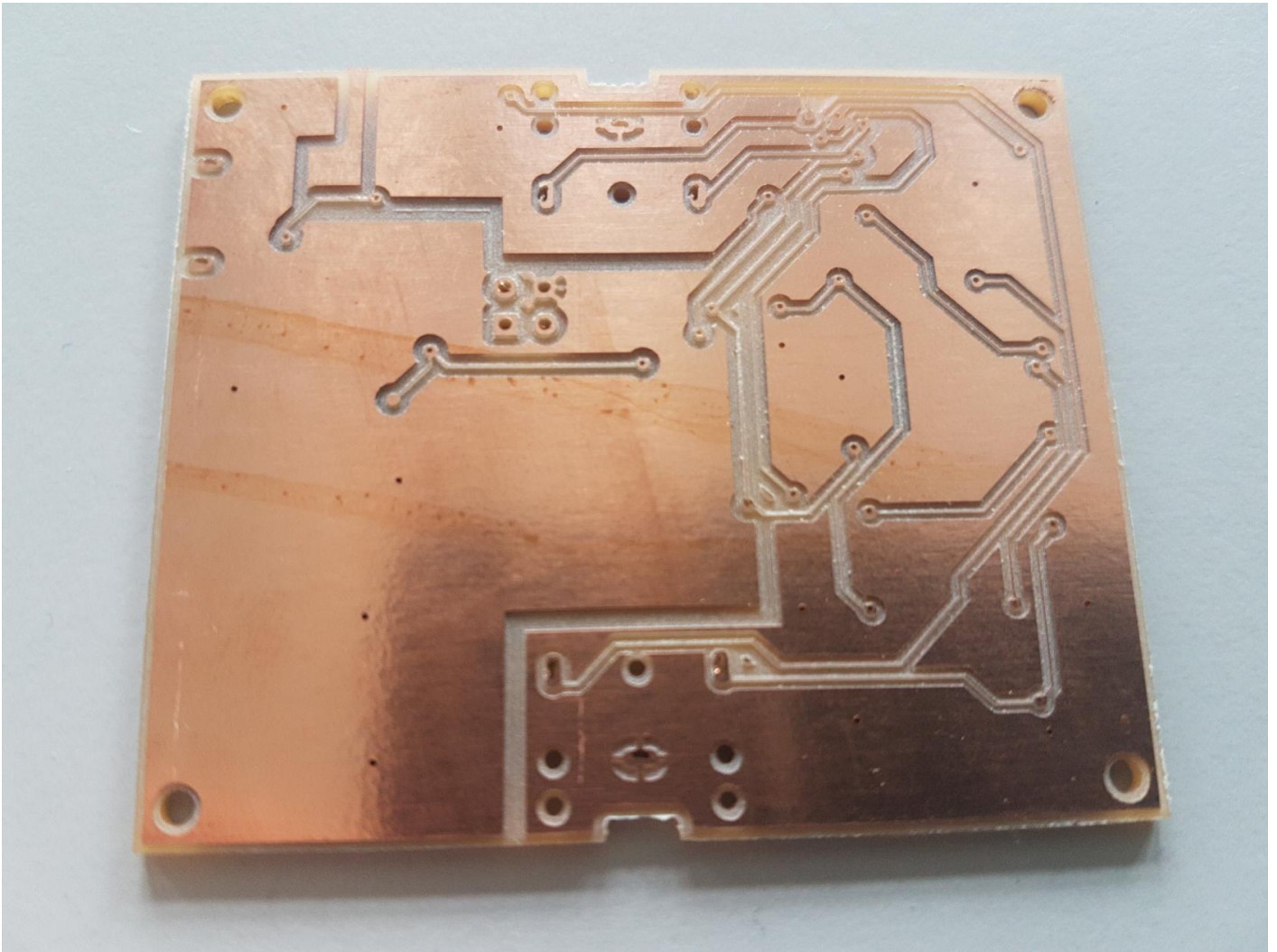
## GaSt Praxisseminar WS

### 25/26



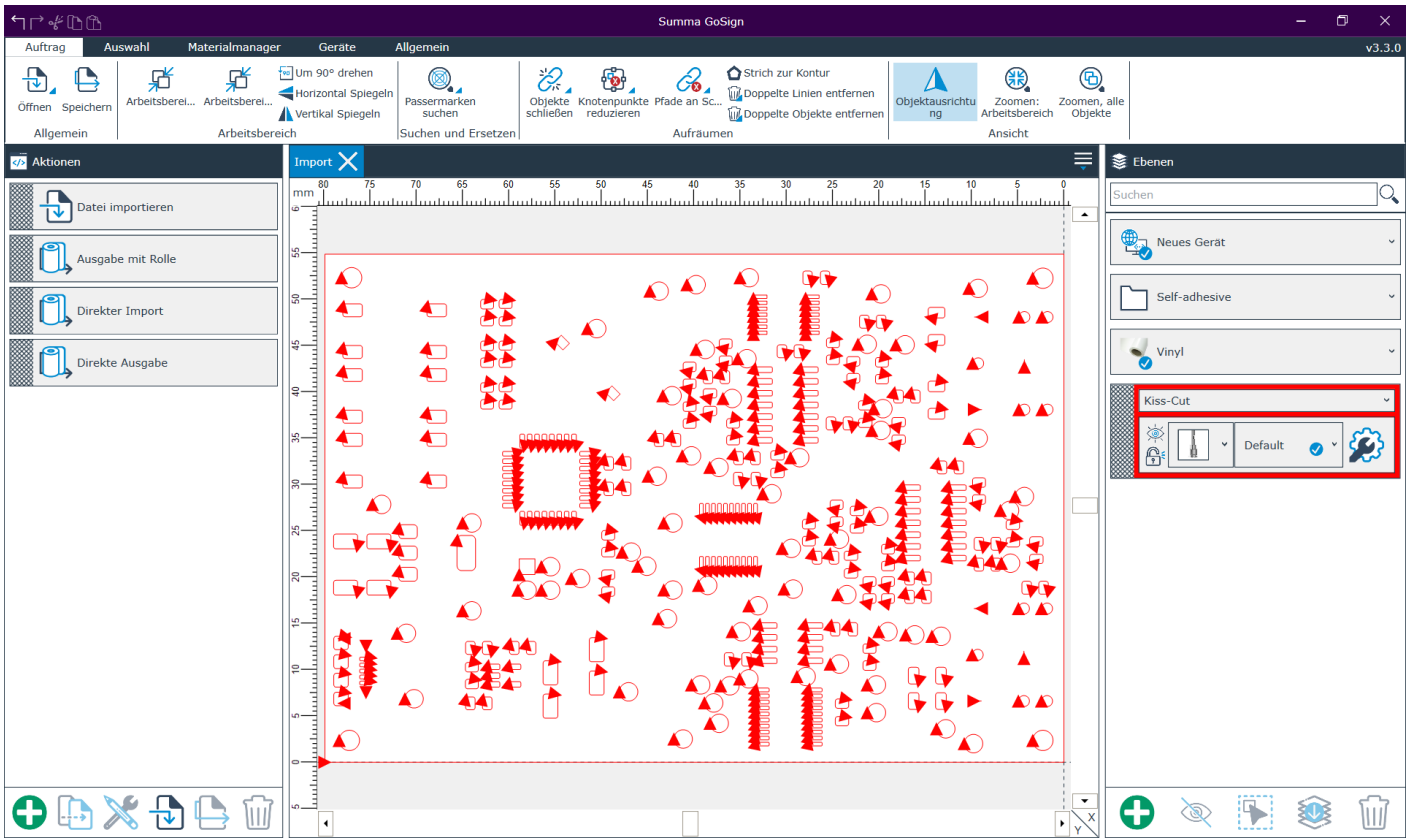
Probably our most complex double sided PCB so far.

Size ~60x50mm

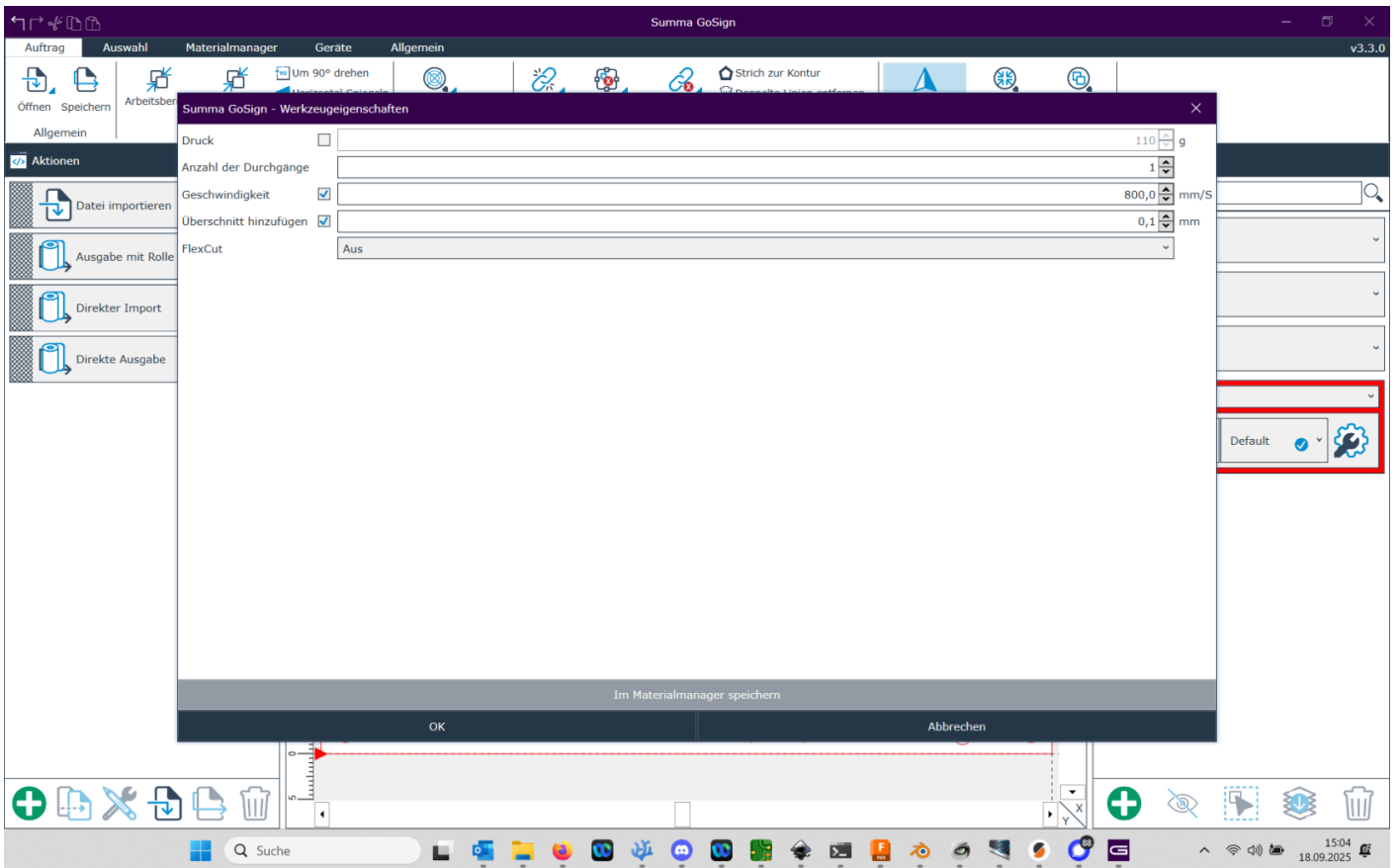


We are working on soldering this board with our Reflow-oven.

We want to try making the solder-paste stencil with our vinyl-cutter:

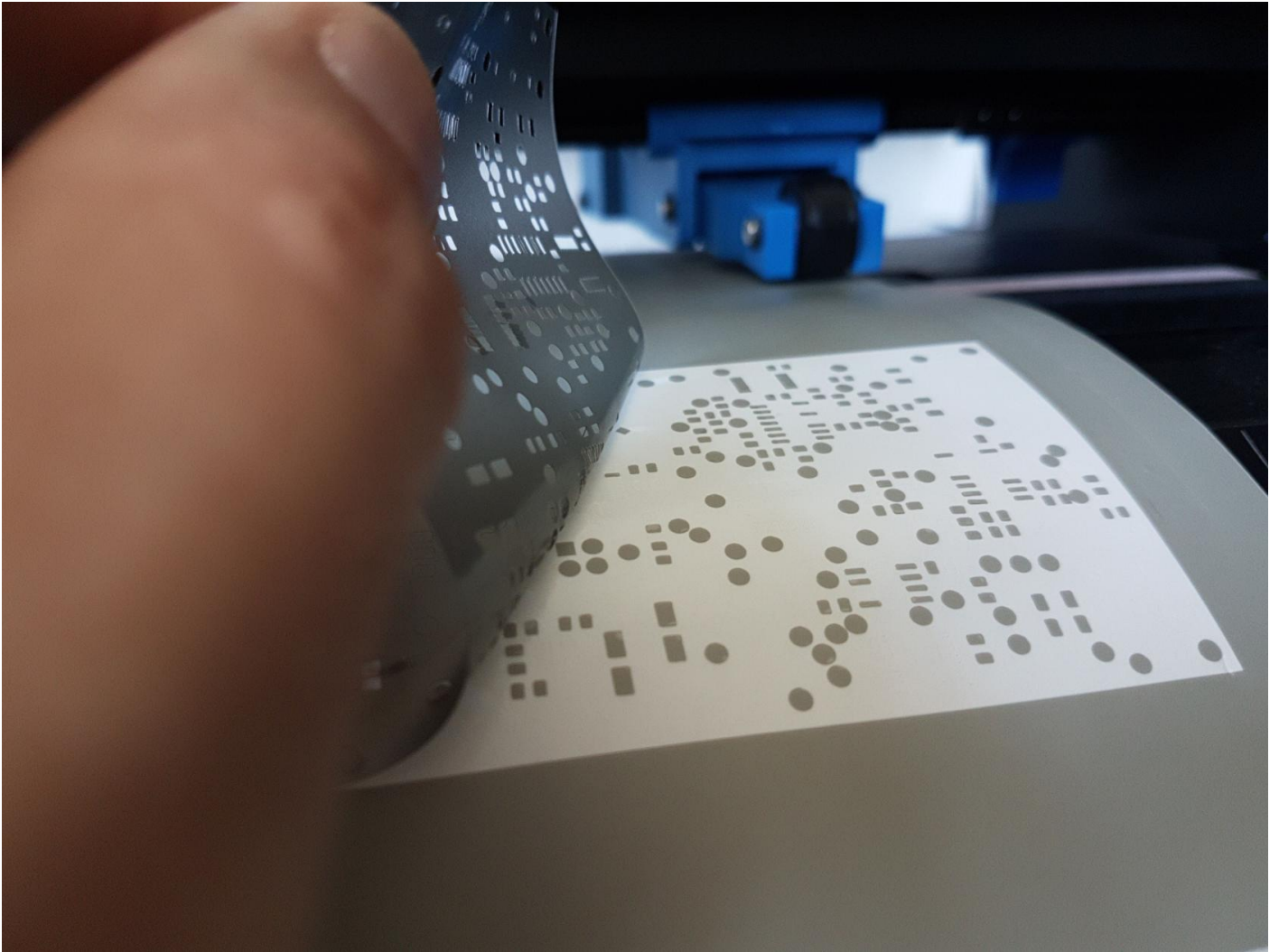


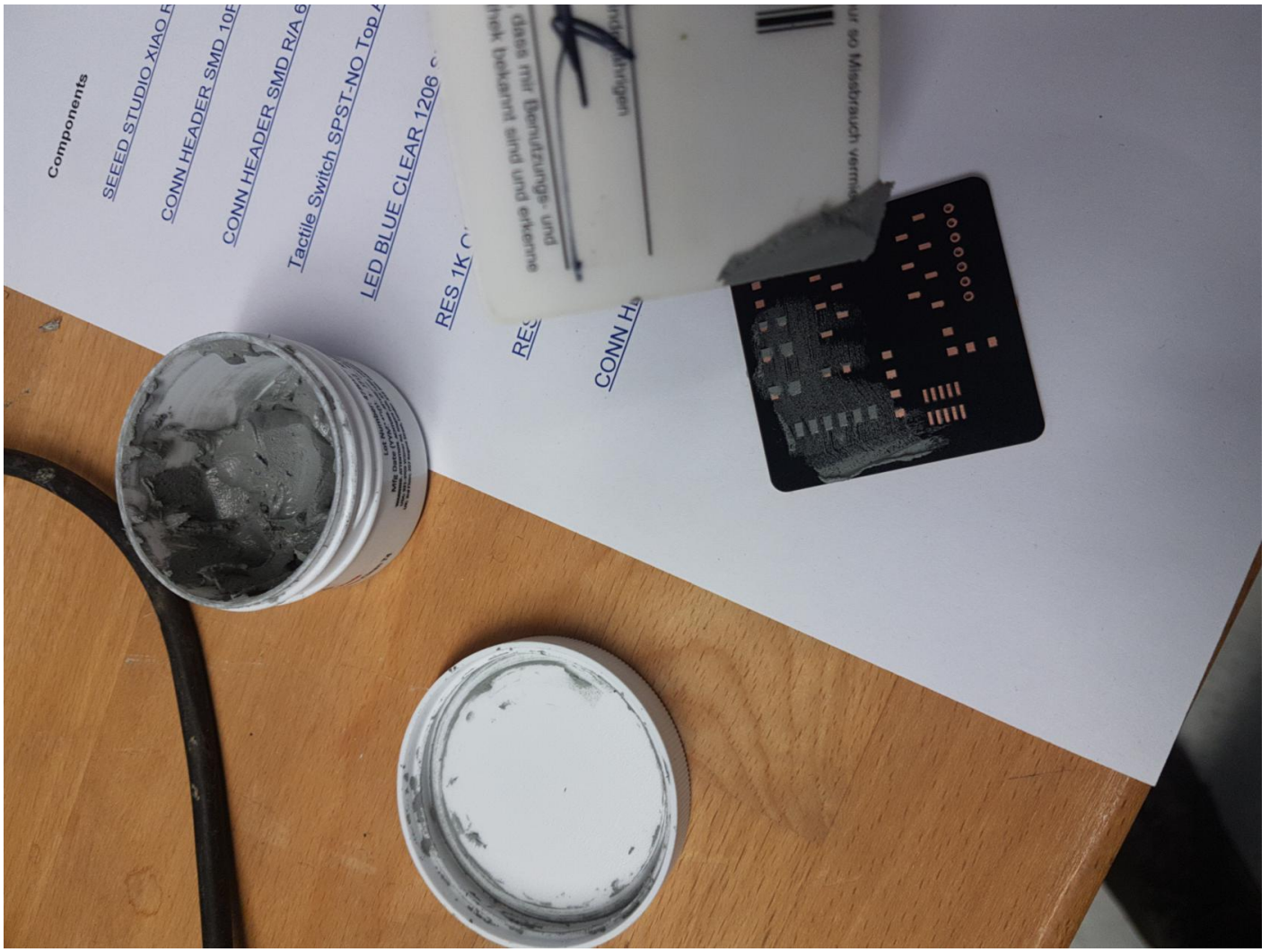
Above is a screenshot from GoSign, our software for the Summa S3 T75.



This is an attempt with a speed of 10mm/s instead of 800mm/s:

The first stencil looks very promising!





Components

SEED STUDIO XIAO R

CONN HEADER SMD 10P

CONN HEADER SMD R/A 6

Tactile Switch SPST-NO Top

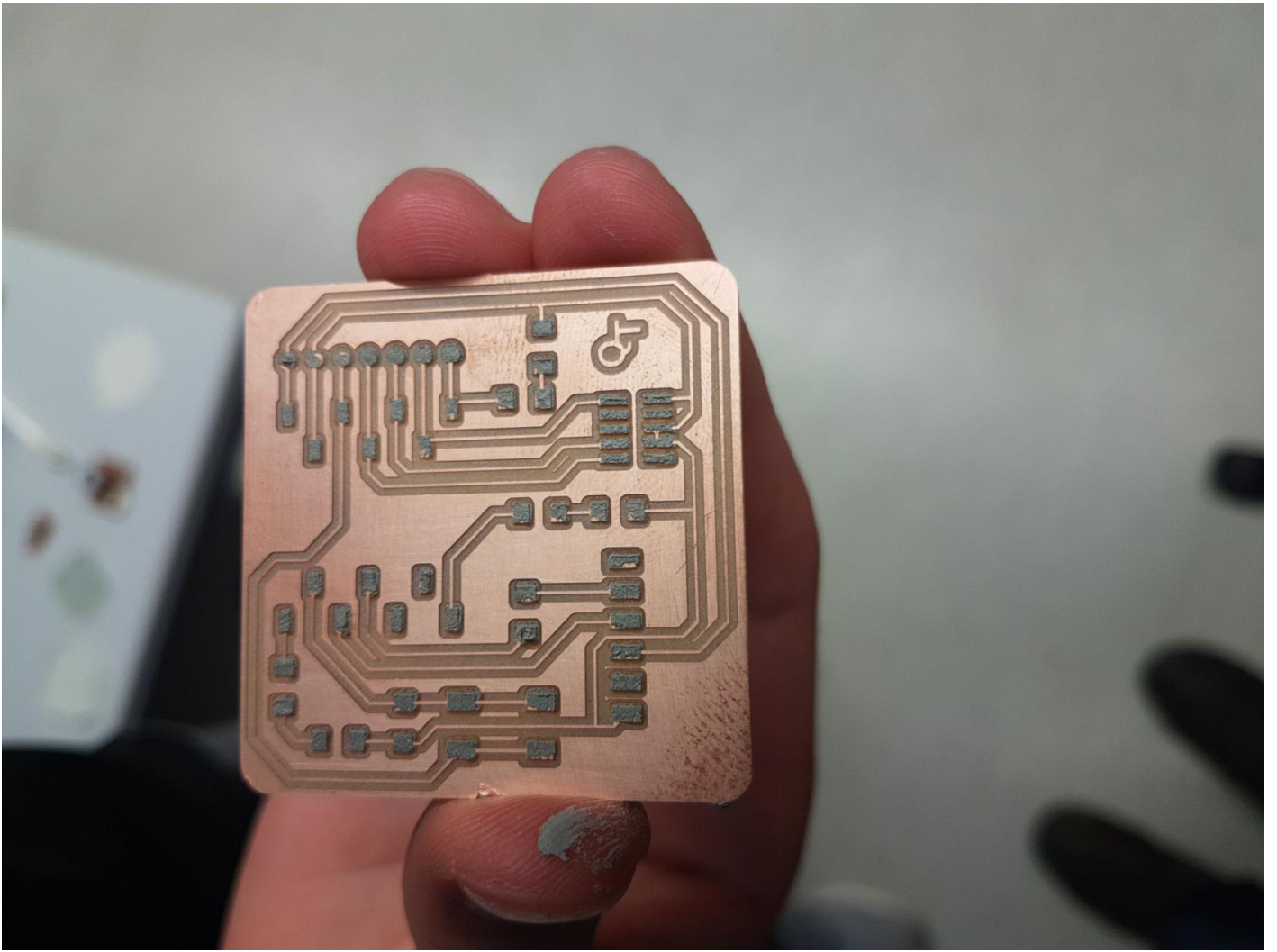
LED BLUE CLEAR 1206

RES 1K

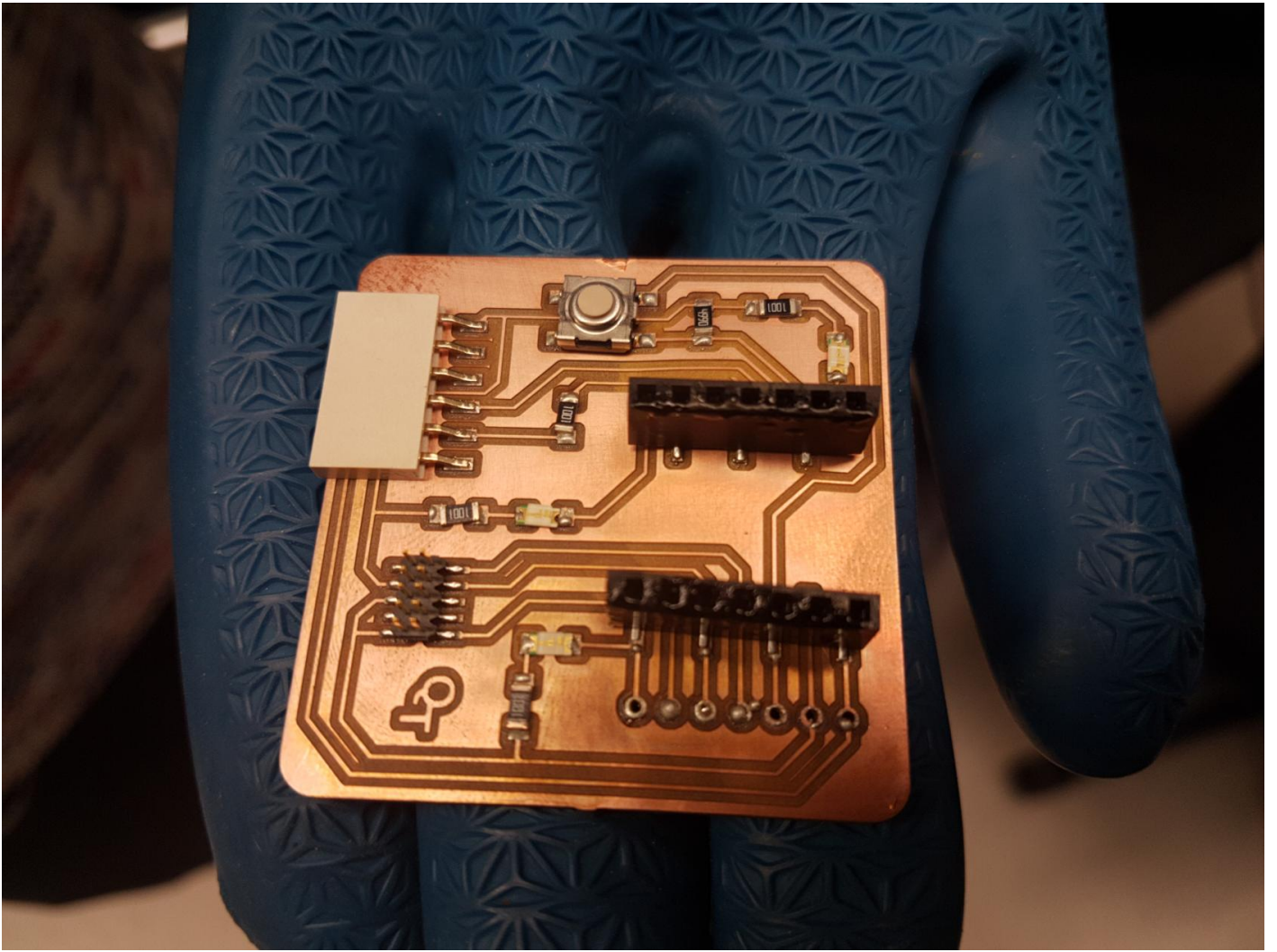
CONN H

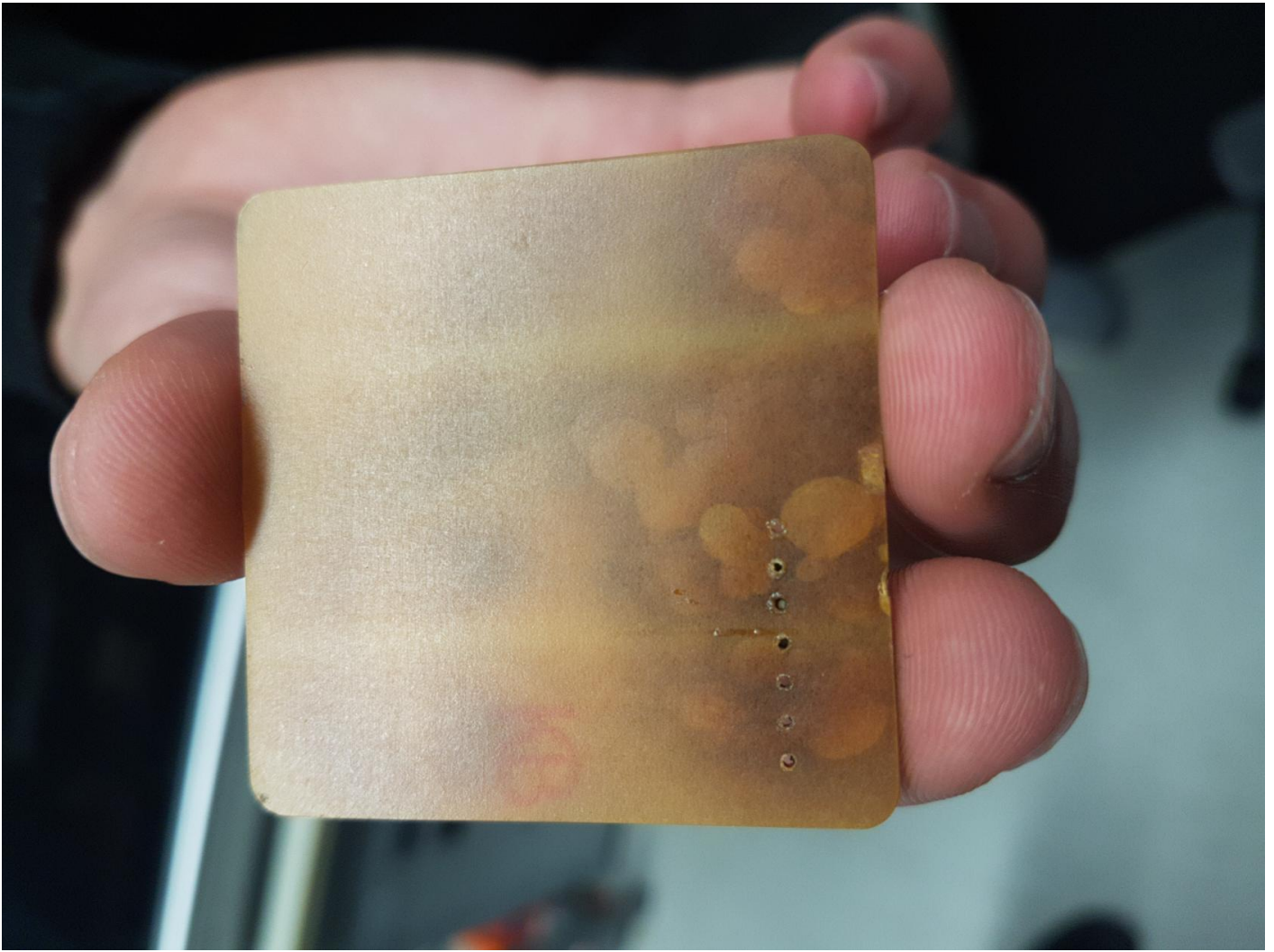
Handwritten signature and German text: "das mit Benutzung und erenne" and "hoch bekannt sind und erkenne"

ur 50 Misbrauch verme



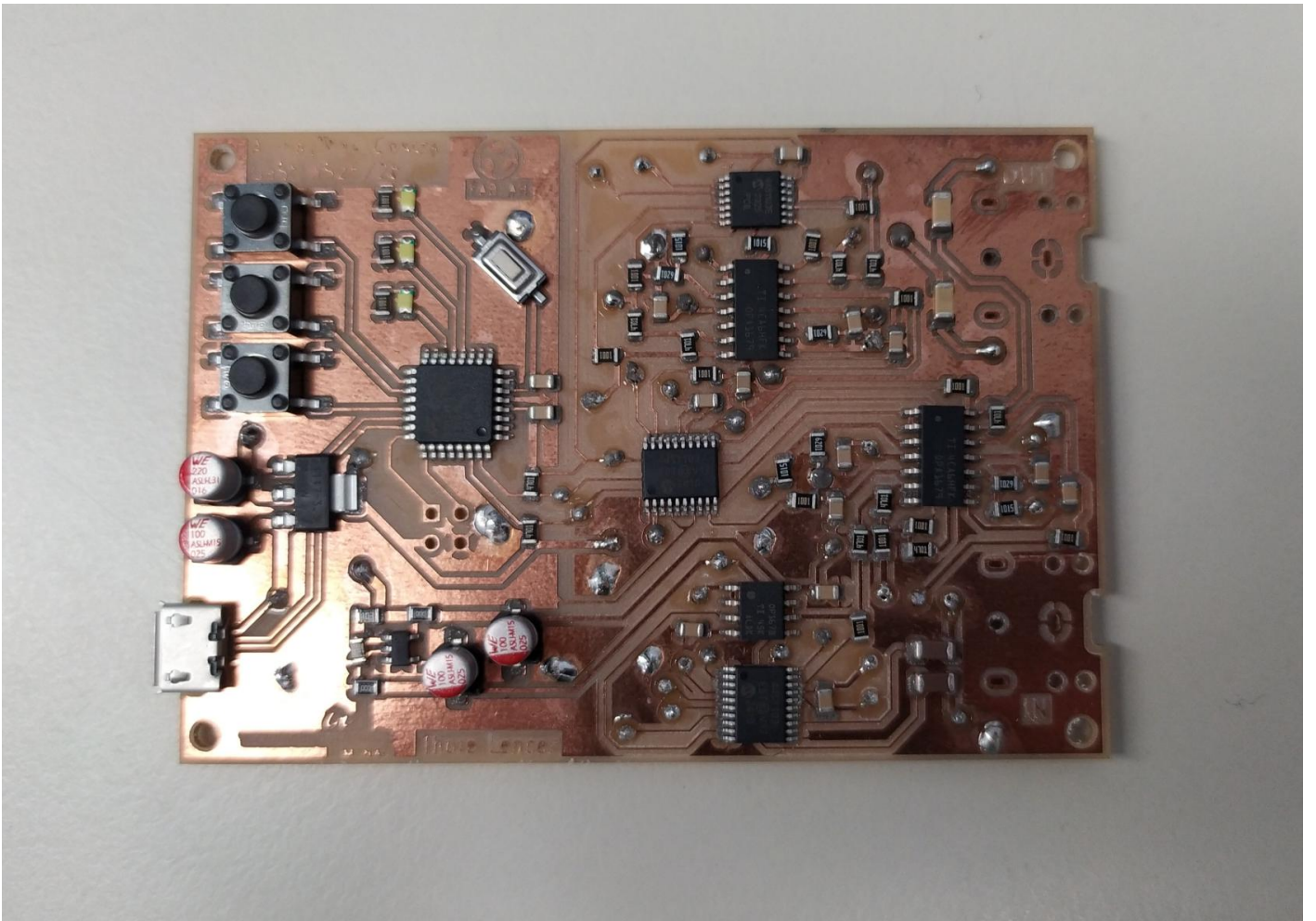
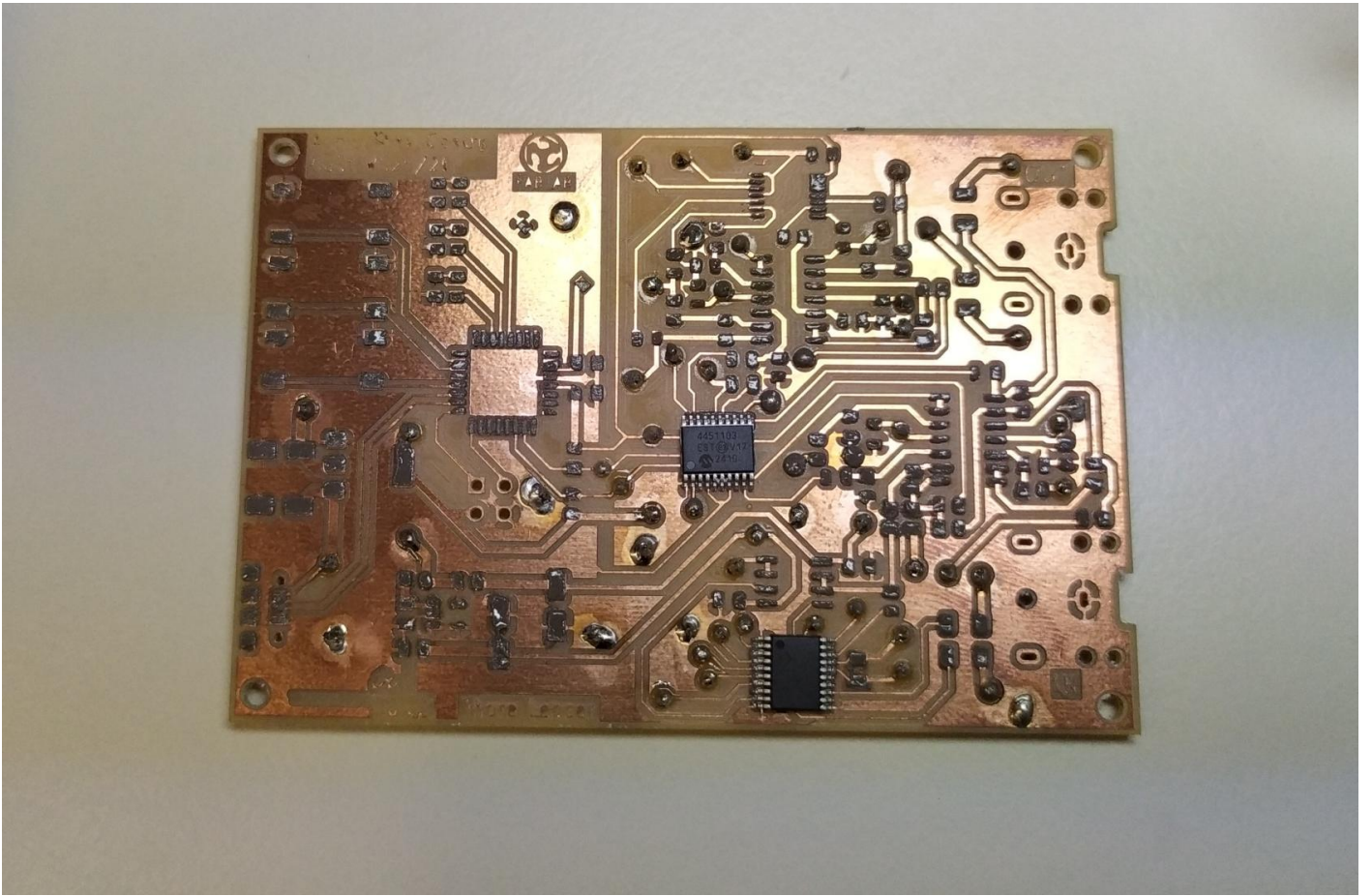






## Reflow soldering

Placing all components:



Good settings for perfect TSSOP package and 0,4mm traces copper milling: 0.2mm v bit but insert 0.25mm in modsproject with 0.25 stepover and 4 offsets

Solder mask removal: Solder mask removal bit; Z calibration with multimeter; then step up by 0,12mm and step down slowly if needed; cure UV mask for 5min first, then mill, then final-cure; cut speed 5mm/s; plunge speed 2mm/s, spindle 6000rpm

Drill after solder mask application! Elsewise solder mask gets into the holes and copper can be destroyed when there are thin pad rings

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Revision #13

Created 2025-09-18 13:00:40 UTC by Ferdi

Updated 2025-10-09 15:01:39 UTC by Ferdi